



Product Change Notice

Micron PCN: 30410
Date: 2/10/2011

Type of Change:	Die Shrink, End of Life	
Title of Change:	576Mb RLDRAM (F37Z) Die Shrink/EOL	
Description of Change:	Micron's 95nm 576Mb RLDRAM (F37Z) is being replaced by 50nm process technology (F67A).	
Reason for Change:	Optimization of Manufacturing Efficiency	
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Product Affected: All 95nm 576Mb RLDRAM (F37Z) based products

Affected Micron Part Number	Replacement Part Number
16x36 CIO	
MT49H16M36BM-18:A	MT49H16M36BM-18:B
MT49H16M36BM-25:A	MT49H16M36BM-25:B
MT49H16M36BM-25E:A	MT49H16M36BM-25E:B
MT49H16M36BM-33:A	MT49H16M36BM-33:B
MT49H16M36FM-18:A	MT49H16M36FM-18:B
MT49H16M36FM-25 IT:A	MT49H16M36FM-25 IT:B
MT49H16M36FM-25:A	MT49H16M36FM-25:B
MT49H16M36FM-25E:A	MT49H16M36FM-25E:B
MT49H16M36FM-33:A	MT49H16M36FM-25:B
MT49H16M36FM-18 IT:A	MT49H16M36BM-18 IT:B
32x18 CIO	
MT49H32M18BM-18:A	MT49H32M18BM-18:B
MT49H32M18BM-25:A	MT49H32M18BM-25:B
MT49H32M18BM-25E:A	MT49H32M18BM-25E:B
MT49H32M18BM-33:A	MT49H32M18BM-33:B
MT49H32M18FM-18:A	MT49H32M18BM-18:B
MT49H32M18FM-25:A	MT49H32M18FM-25:B
MT49H32M18FM-25E:A	MT49H32M18FM-25E:B
MT49H32M18FM-33:A	MT49H32M18FM-33:B
64x9 CIO	
MT49H64M9BM-25:A	MT49H64M9BM-25:B
MT49H64M9BM-25E IT:A	MT49H64M9BM-25E IT:B
MT49H64M9BM-33:A	MT49H64M9BM-25:B
MT49H64M9FM-25:A	MT49H64M9FM-25:B
MT49H64M9FM-25E:A	MT49H64M9FM-25E:B
MT49H64M9FM-33:A	MT49H64M9FM-25:B

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change



32x18 SIO

MT49H32M18CBM-18:A	MT49H32M18CBM-18:B
MT49H32M18CBM-25:A	MT49H32M18CBM-25:B
MT49H32M18CBM-25E:A	MT49H32M18CBM-18:B
MT49H32M18CBM-33:A	MT49H32M18CBM-25:B
MT49H32M18CFM-18:A	MT49H32M18CFM-18:B
MT49H32M18CFM-25:A	MT49H32M18CFM-25:B
MT49H32M18CFM-25E:A	MT49H32M18CFM-25E:B
MT49H32M18CFM-33:A	MT49H32M18CFM-25:B

64x9 SIO

MT49H64M9CBM-25E:A	MT49H64M9CBM-25E:B
MT49H64M9CBM-33:A	MT49H64M9CBM-25E:B
MT49H64M9CFM-33:A	MT49H64M9CFM-25:B
MT49H64M9BM-18:A	Contact Factory

Method of Identification:

The die designator in the marketing part number will change from A to **B**. Please see example below.

<u>Affected Micron Part Number</u>	<u>Replacement Part Number</u>
MT49H16M36BM-18:A	MT49H16M36BM-18: B

Manufacturing Sites Affected**50nm Product (F67A)**

Fabrication: Singapore

Assembly: Japan

Product/Data Availability**50nm Product (F67A)**

<u>F67A Config</u>	<u>Samples Available</u>	<u>Qual Data Available</u>	<u>Production Shipments</u>
16x36 CIO	March 2011	May 2011	May 2011
32x18 CIO	March 2011	May 2011	May 2011
64x9 CIO	April 2011	June 2011	June 2011
32x18 SIO	May 2011	June 2011	June 2011
64x9 SIO	June 2011	July 2011	July 2011

95nm Product (F37Z)

Last Time Buy: December 31, 2011

Last Time Ship: June 30, 2012
